



# NC257-2 SN100C<sup>®</sup>



## Lead-Free Solder Paste

### Features:

- RoHS Compliant
- Vapor Phase Compatible
- Excellent Wetting
- Broad Printing Process Window
- Low-Tombstoning
- No Head-in-Pillow
- Clear Pin-Probe Testable Residue
- 24 Hour Stencil Life
- Low Solder Beading
- Reduces Voiding Under Micro-BGAs
- 12-14 Hour Tack Time
- General Metal Load 88.5%

### Description:

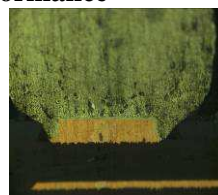
NC257-2 has been developed to offer extremely broad process windows for printing, wetting and pin-probe testing. The superior wetting ability of NC257-2 results in bright, smooth and shiny solder joints, and it has been specifically formulated to lower solder beading. It also offers very low post process residues, which remain crystal clear and easily probed even at the elevated temperatures required for today's lead-free alloys. This solder paste offers a chemistry developed for use in air reflow, as well as providing slump and humidity tolerances to extend the useable life in facilities where environmental control is not at its optimum.

### Comparisons:

#### Improved Wetting Performance



Competitor A



AIM NC257-2

#### Via Void Reduction Properties

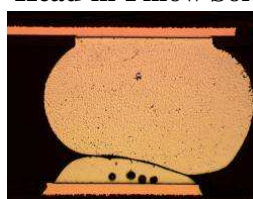


Competitor I



AIM 257-2

#### Head-in-Pillow Solder Joint Elimination



Competitor A



AIM 257-2

### Printing:

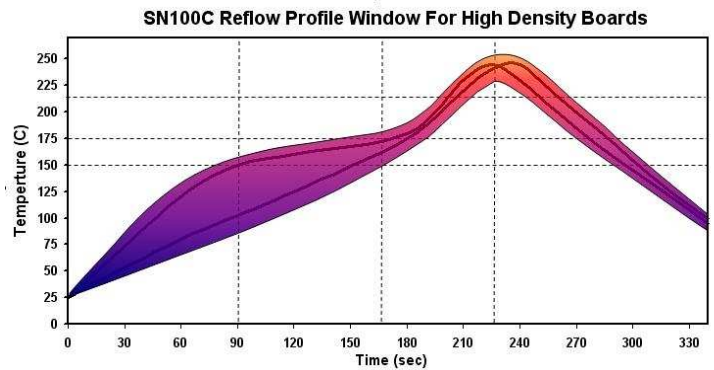
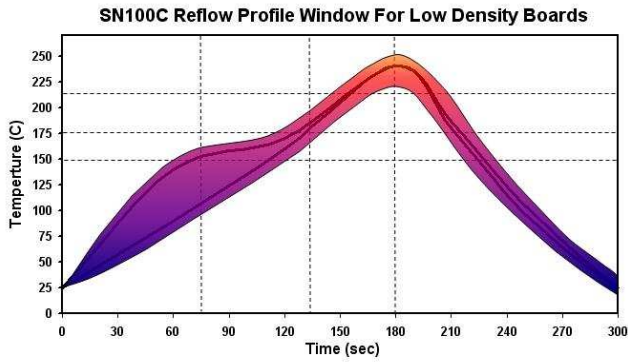
- Apply sufficient paste to the stencil to allow a smooth, even roll during the print cycle (a bead diameter of 12 to 16 mm (½ to ⅝ inch) is normally sufficient to begin).
- Apply small amounts of fresh solder paste to the stencil at controlled intervals to maintain paste chemistry and workable properties.
- NC257-2 provides the necessary tack time and force for today's high speed placement equipment, which will enhance product performance and reliability.

#### RECOMMENDED INITIAL PRINTER SETTINGS BELOW ARE DEPENDENT ON PCB AND PAD DESIGN

PARAMETER	RECOMMENDED INITIAL SETTINGS	PARAMETER	RECOMMENDED INITIAL SETTINGS
Squeegee Pressure	0.10-0.30 kg/cm (.6 - 1.7 lbs/In.) of blade	PCB Separation Distance	0.75-2.0 mm (.030-.080")
Squeegee Speed	12-150 mm/sec (.5-6"/sec)	PCB Separation Speed	Slow
Snap-off Distance	On Contact 0.00 mm (0.00")		

## Reflow Profile:

Two unique profile families are depicted below; both can be used in ramp-spike or ramp-soak-spike applications, and they each have similar reflow temperatures. The two profiles differ in where they reach their respective peak temperatures, as well as the time above liquidus (TAL). The shorter profile of the two would apply to smaller assemblies, where as the longer profile would apply to larger assemblies, such as backplanes or high-density boards. The shaded area defines the process window. Oven efficiency, board size/mass, component type and density all influence the final profile for a given assembly. These profiles are starting points, and processing boards with thermal-couples attached is recommended to optimize the process.



<i>RATE OF RISE 2°C / SEC MAX</i>	<i>RAMP TO 150°C (302°F)</i>	<i>PROGRESS THROUGH 150°C-175°C (302°F-347°F)</i>	<i>TO PEAK TEMP 235°C-255°C (455°F-492°F)</i>	<i>TIME ABOVE 227°C (442°F)</i>	<i>COOLDOWN ≤ 4 °C / SEC</i>	<i>PROFILE LENGTH AMBIENT TO PEAK</i>
Short Profiles	≤ 75 Sec	30-60 Sec	45-75 Sec	30-60 Sec	45± 15 Sec	2.75-3.5 Min
Long Profiles	≤ 90 Sec	60-90 Sec	45-75 Sec	60-90 Sec	45± 15 Sec	4.5-5.0 Min

- ❖ THE RECOMMENDED REFLOW PROFILE FOR NC257-2 IS PROVIDED AS A GUIDELINE. OPTIMAL PROFILE MAY DIFFER DUE TO OVEN TYPE, ASSEMBLY LAYOUT, OR OTHER PROCESS VARIABLES. CONTACT AIM TECHNICAL SUPPORT IF YOU REQUIRE ADDITIONAL PROFILING ASSISTANCE.
- ❖ THE REFLOW PROFILE FOR THE SN100C<sup>®</sup> PASTES USING A VAPOR PHASE REFLOW OVEN: PEAK TEMPERATURE RANGE IS 230°C – 245°C.

## Compatible Products:

- AIM Lead-Free Electropure Solder Bar
- NC Paste Flux, No Clean Tacky Flux
- NC270 VOC-Free No Clean Spray Flux
- NC264-5 No Clean flux Spray/Foam
- Glowcore – No Clean Cored Wire
- One-Step Underfill Epoxy 688
- Epoxy 4044 – Chip Bonding Epoxy
- 200AX – Stencil Cleaner

## Cleaning:

- NC257-2 can be cleaned if necessary with saponified water or an appropriate solvent cleaner.
- Please refer to the AIM cleaner matrix for a list of compatible cleaning materials.

## Handling and Storage:

- NC257-2 is best used within 1 year at 4° C-12° C (40° F-55° F) or 6 months at room temperature.
- Allow the solder paste to warm up completely and naturally to ambient temperature (8 hrs.) prior to breaking the seal for use.
- Mix the product lightly and thoroughly (1-2 mins. max) to ensure even distribution of any separated material.
- Do not store new and used paste in the same container, and reseal any opened containers while not in use.
- Replace the internal plug and cap of the 500 gram jars to ensure the best possible seal.

## Physical Properties:

ITEM	SPECIFICATION
Appearance	Gray, Smooth, Creamy
Alloy	SN100C <sup>®</sup>
Melting Point	227°C
Particle Size	T3, T4, T5
Metal Loading	88.5% (T3)
Viscosity	Print/Dispense Versions Available
Packaging	Available in all industry standard packaging.

## Test Data Summary:

CLASSIFICATION																		
Product Name	IPC Classification to J-STD-004	Copper Mirror to J-STD-004	Silver Chromate to J-STD-004															
NC257-2	ROLO	LOW	DISSOLVE 35% - PASS															
POWDER TESTING																		
No.	Item	Results	Test Method															
1	Powder Size	Type 3 – 45-25 micron, Type 4 – 38-20 micron	IPC TM 650 2.2.14															
2	Powder Shape	Spherical	Microscope															
FLUX MEDIUM TESTING																		
No.	Item	Results	Test Method															
1	Acid Value	150.02 mg KOH/ g flux	J-STD-004 IPC TM 650 2.3.13															
2	Halide Content	<300 ppm	J-STD-004 IPC TM 650 2.3.35															
3	Fluorides Spot Test	No fluoride	J-STD-004 IPC TM 650 2.3.35.1 J-STD-004 IPC TM 650 2.3.35.2															
4	Corrosivity Test/ Copper Mirror	L	J-STD-004 IPC TM 650 2.3.32															
5	Corrosion Flux	Pass	J-STD-004 IPC TM 650 2.6.15															
6	Halide-Free/Silver Chromate Paper Test	Pass	J-STD-004 IPC TM 650 2.3.33															
7	Surface Insulation Resistance	>85° C, 85% RH:  <table border="0"> <tr> <td></td> <td>Control:</td> <td>Samples:</td> </tr> <tr> <td>Initial</td> <td>9.69E+13Ω</td> <td>3.88E+13Ω</td> </tr> <tr> <td>24 hrs</td> <td>8.60E+09Ω</td> <td>1.87E+08Ω</td> </tr> <tr> <td>96 hrs</td> <td>7.04E+09Ω</td> <td>5.29E+08Ω</td> </tr> <tr> <td>168 hrs</td> <td>5.92E+09Ω</td> <td>1.02E+09Ω</td> </tr> </table> - No dendrite growth or corrosion, after a visual inspection – Pass All Criteria		Control:	Samples:	Initial	9.69E+13Ω	3.88E+13Ω	24 hrs	8.60E+09Ω	1.87E+08Ω	96 hrs	7.04E+09Ω	5.29E+08Ω	168 hrs	5.92E+09Ω	1.02E+09Ω	J-STD-004 IPC TM 650 2.6.3.3
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8	Telcordia (Bellcore) SIR	35°C,85% 4 days Initial: 8.43E+12Ω      Final : 8.30E+12Ω Requirement > 1.0E+10Ω - Pass	GR-78-CORE															
9	Telcordia (Bellcore) Electromigration	65°C,85% 500 hrs Initial: 1.94E+10Ω      Final : 2.08E+10Ω R <sub>f</sub> /R <sub>i</sub> > 0.1 - Pass	GR-78-CORE															
10	Compatibility Test	See list of recommended products above	GR-78-CORE															
VISCOSITY TESTING																		
No.	Item	Results	Test Method															
1	T-Bar Spindle Test Method	670 ± 10% kcps	J-STD-005 IPC TM 650 2.4.34															
SOLDER PASTE TESTING																		
No.	Item	Results	Test Method															
1	Tack Test	32.8 gf	J-STD-005 IPC TM 650 2.4.44															
2	Tack Test	94.8 gf	JIS Z 3284 Annex 9															
3	Solder Ball Test	Pass	J-STD-005 IPC TM 650 2.4.43															
4	Wetting Test	Pass	J-STD-005 IPC TM 650 2.4.45															
5	Paste Shelf Life	4°C (39°F) = 9 months	AIM TM 125-11															
6	Solder Paste Slump Test	Pass	J-STD-005 IPC TM 650 2.4.35															

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